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Sekimoto

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(54) **SEMICONDUCTOR ELEMENT**

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(73) Assignee: **Sony Corporation**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/130,541**

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(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Search** D13/182; 174/524, 174/525; 257/690; 361/752, 798, 820, 748, 736, 737, 761

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(57) **CLAIM**

The ornamental design for a semiconductor element, as shown and described.

DESCRIPTION

FIG. **1** is a top, front perspective view of a semiconductor element showing my new design;
FIG. **2** is a front elevational view thereof; and,
FIG. **3** is a rear elevational view thereof.
Portions in broken lines are for illustrative purposes only and form no part of claimed design.

1 Claim, 2 Drawing Sheets

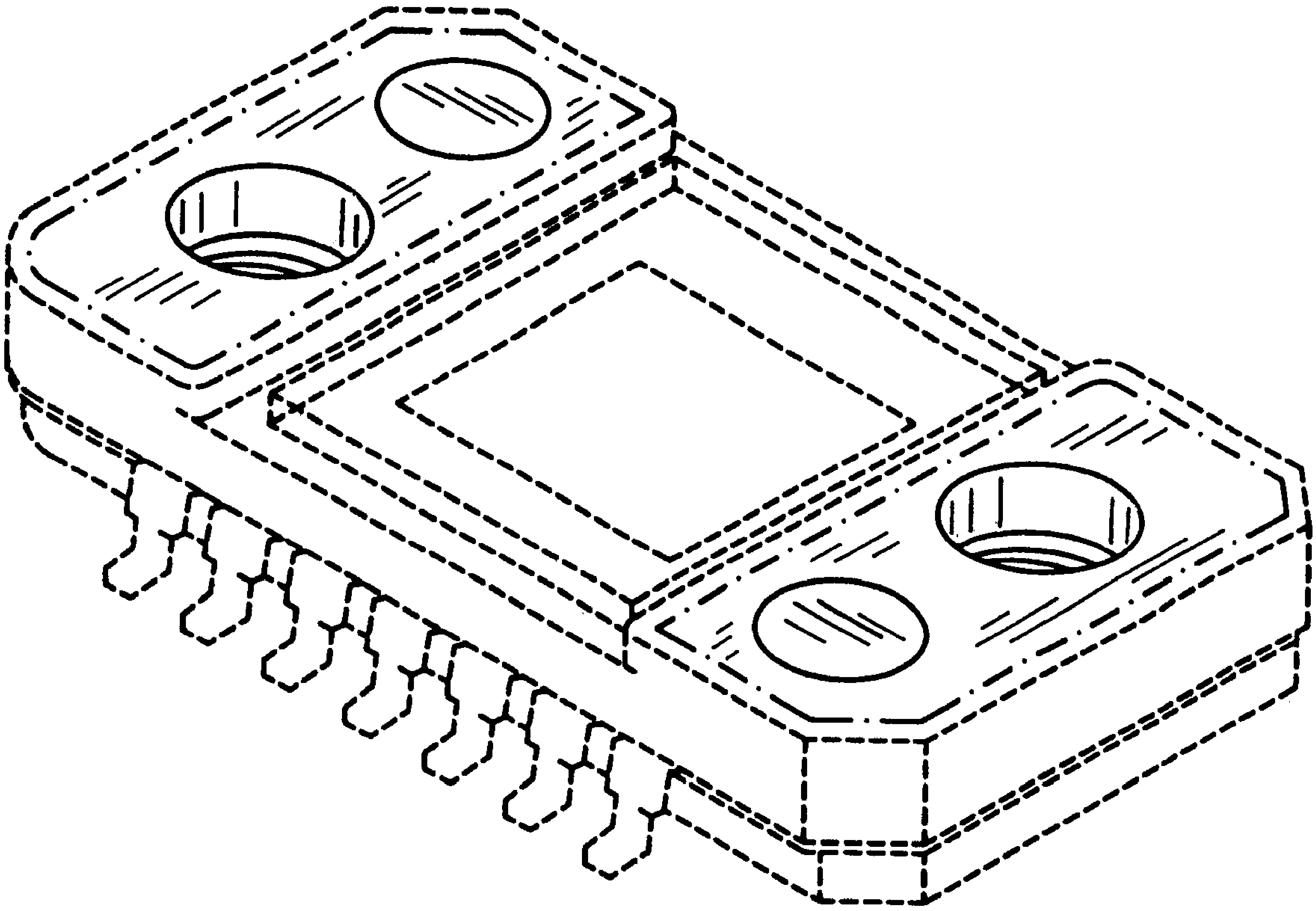

FIG. 1

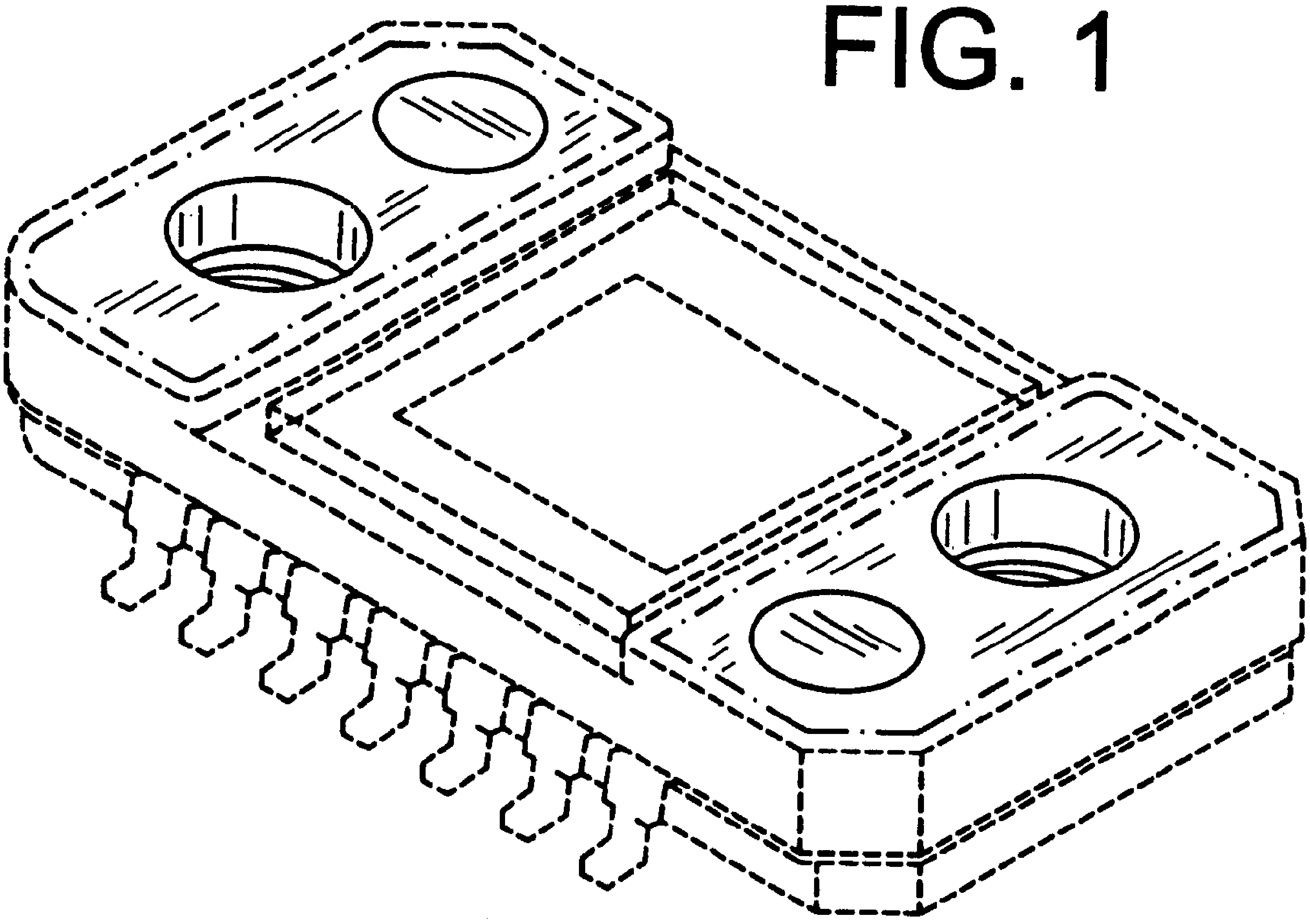

FIG. 2

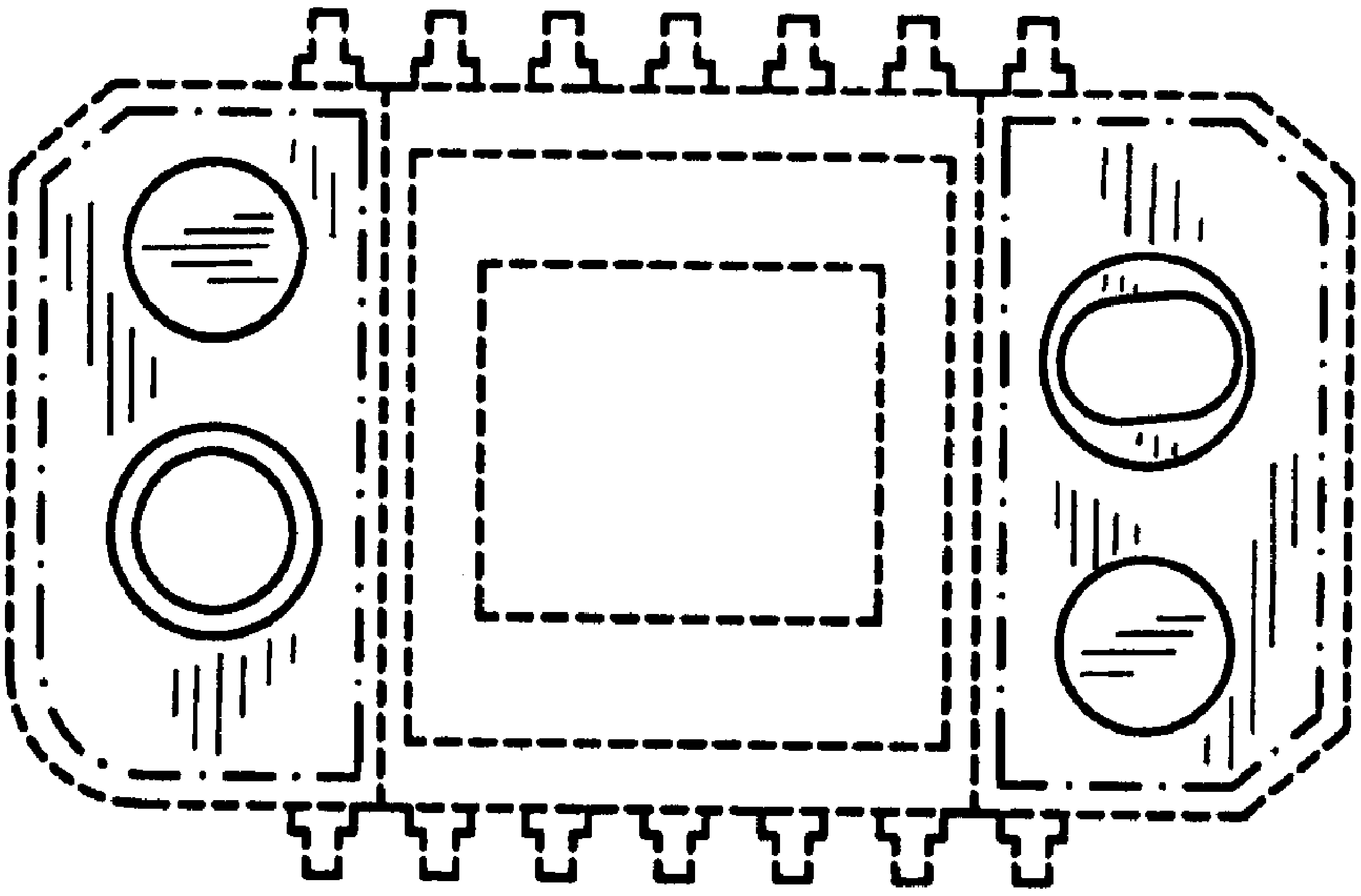

FIG. 3